

**MAY 24-27, 2026**  
International Convention Center  
SHANGHAI CHINA

**Call for CAS/EDS Cross-Society  
Special Session Papers**  
**“Flexible Circuits and Systems for an  
Intelligently Interactive World”**

**Oct. 12 2025**

**Paper Submission**

**Jan. 19 2026**

**Author Notification**

**Feb. 9 2026**

**Final Submission**

## About ISCAS-2026:

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society. ISCAS 2026 will be held in Shanghai, China, from May 24 to 27, 2026, inspired by the theme "Circuits and Systems for Intelligent Society".

## CALL FOR PAPERS

The rapid evolution of technology in recent years has led to the emergence of the Era of Everything Intelligence, where interconnected devices and systems interact seamlessly to enhance various aspects of our lives. This special session aims to explore the critical role of flexible circuits and systems in realizing the vision of a Smart Interface – a versatile and adaptable platform that enables intelligent interactions between humans, machines, and the environment. This session will bring together researchers, engineers, and experts from academia and industry to discuss and share their latest advancements, challenges, and innovative solutions in the field.

**\* Selected papers will be invited for possible publications in IEEE Journal on Flexible Electronics (J-FLEX). The presentation video will be available to attendees in both ISCAS and IFETC.**

### The proposed session includes the following topic:

- Flexible Electronics for Wearable and Implantable Devices
- Sensor Integration and Data Fusion in Flexible Systems
- Energy Harvesting and Power Management in Flexible Circuits
- Bioelectronics and Neural Interfaces on Flexible Substrates
- Human-Machine Interaction and Interface Design
- Stretchable and Bendable Electronics for Internet of Things (IoT)
- Printed Electronics and Additive Manufacturing Techniques
- Machine Learning and AI for Flexible System Optimization
- Novel Materials and Fabrication Processes for Flexible Circuits
- Security and Privacy in Smart Interfaces

### Organizers:

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Tong Ge	Nanyang Tech. Univ., Singapore
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